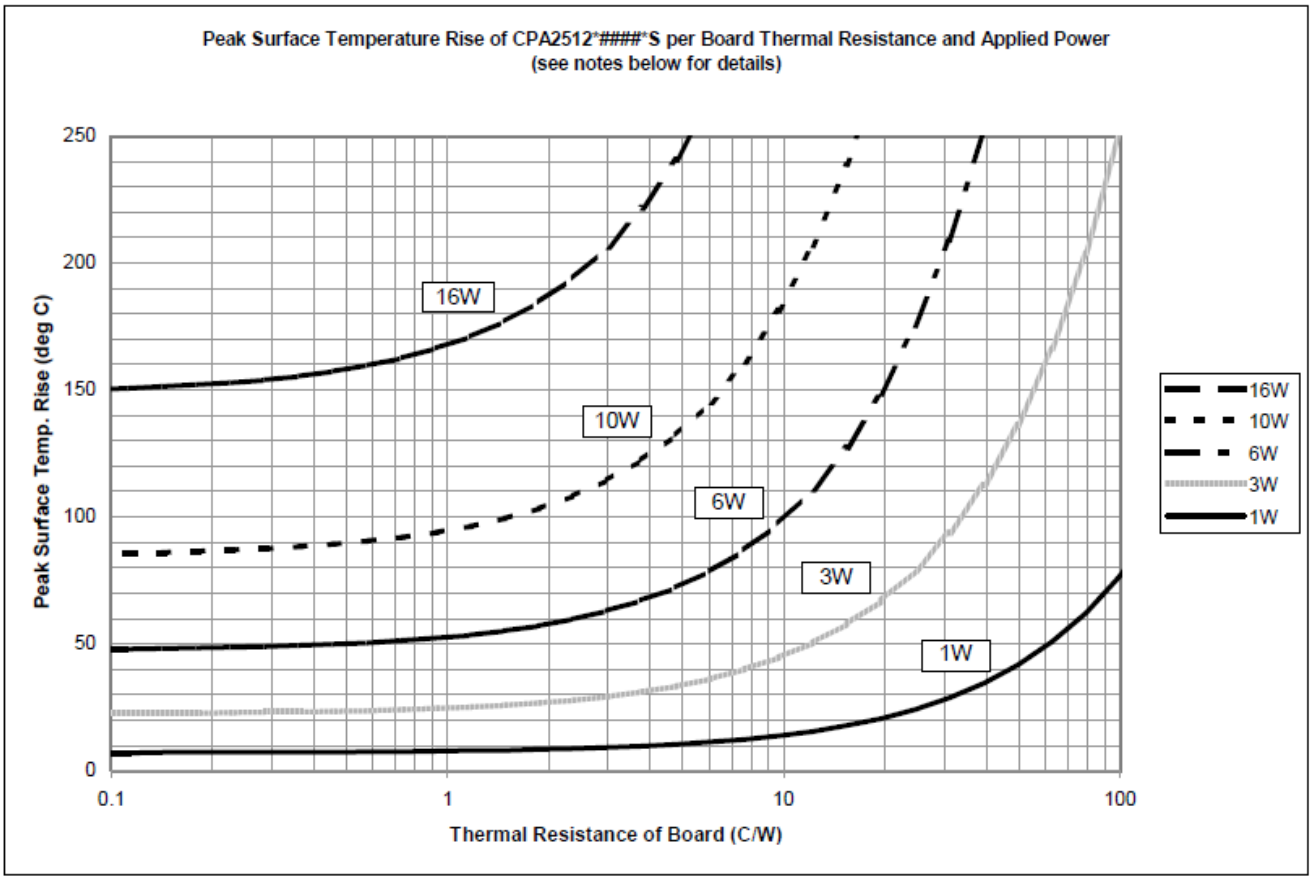
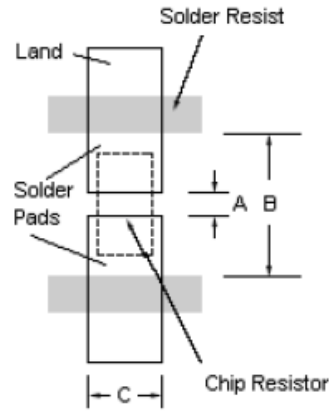
Thermal Performance:



Notes:

- Plots produced by characterization of thermal coefficients determined from experimental measurements (by thermal imaging camera) at thermal equilibrium with parts mounted to various boards (with homogeneous thermal conductivity to minimize uncertainty) per recommended solder pad dimensions and with boards pressed against a Cu carrier/heat-sink (not ideal) with a thermal compound interface in a static environment (no air flow).
- Heat flow primarily through thickness of board with virtually zero lateral heat transfer in board.
- Thermal resistance of test boards were calculated based on material manufacturer specified thermal conductivity (20ºC) via the following: Thermal Resistance (ºC/W) = L / (k • A), where Thermal Conductivity, k (W/m•K) = (L / (A • ΔT)) • ΔQ/Δt, L = Thickness of board in meters and A = area of chip resistor in meters (2512 size = 6.3x3.2mm)
- The relationships between peak surface temperature rise, power, and board thermal resistance are linear, but the x-axis is plotted in log-scale to offer greater resolution at lower board thermal resistances.

Recommended Solder Pad Dimensions:



	Standard Dimensions (mm)
Size: Inch (Metric)	2512 (6332)
A	1.6
B	7.7
C	3.5